


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	IPD/15/9212	
<b>1.3 Title of PCN</b>	L6699 (Product Line U340) : Metal mask modification	
<b>1.4 Product Category</b>	Advanced controller	
<b>1.5 Issue date</b>	2015-04-30	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
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<b>2.2.1 Product Manager</b>	Francesca Marta SANDRINI
<b>2.1.2 Marketing Manager</b>	Vincenzo MONTEMEZZO
<b>2.1.3 Quality Manager</b>	Paolo MORETTI

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Die redesign	Functional / pin layout change	Ang Mo Kio, Singapore

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	U340BC6	U340BD6
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	No impact.	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	To enlarge the pin Line functionality with dv/dt lower than 100V/second
<b>5.2 Customer Benefit</b>	QUALITY IMPROVEMENT

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	By a new Finished Goods code. L6699D-6/ L6699DTR-6/
------------------------	---

**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2015-04-20
<b>7.2 Intended start of delivery</b>	2015-10-05
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	U340 Reliability Report.pdf		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2015-04-30

**9. Attachments (additional documentations)**

**10. Affected parts**

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	L6699D	
	L6699DTR	

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## Public Products List

**PCN Title** : L6699 (Product Line U340) : Metal mask modification

**PCN Reference** : IPD/15/9212

**PCN Created on** : 20-Apr-2015

**Subject** : Public Product List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.



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## **L6699 (Product Line U340) : Metal mask modification**

### **WHAT is the change?**

The Internal Supply Rail of the Line Comparator has been changed. See the following pages.

### **WHY?**

The change was made to solve the following issue:

A signal applied to the Line pin with a slope lower than 100V/second could cause the device stops switching even though the voltage at Line pin is higher than its threshold ( 1.25V ).

### **WHEN will this change occur?**

Tentatively at the beginning of Q4 2015. However the production of the new product will be based on material availability and customers' orders. Phase-out and phase-in will be done accordingly.

### **HOW will the change be qualified?**

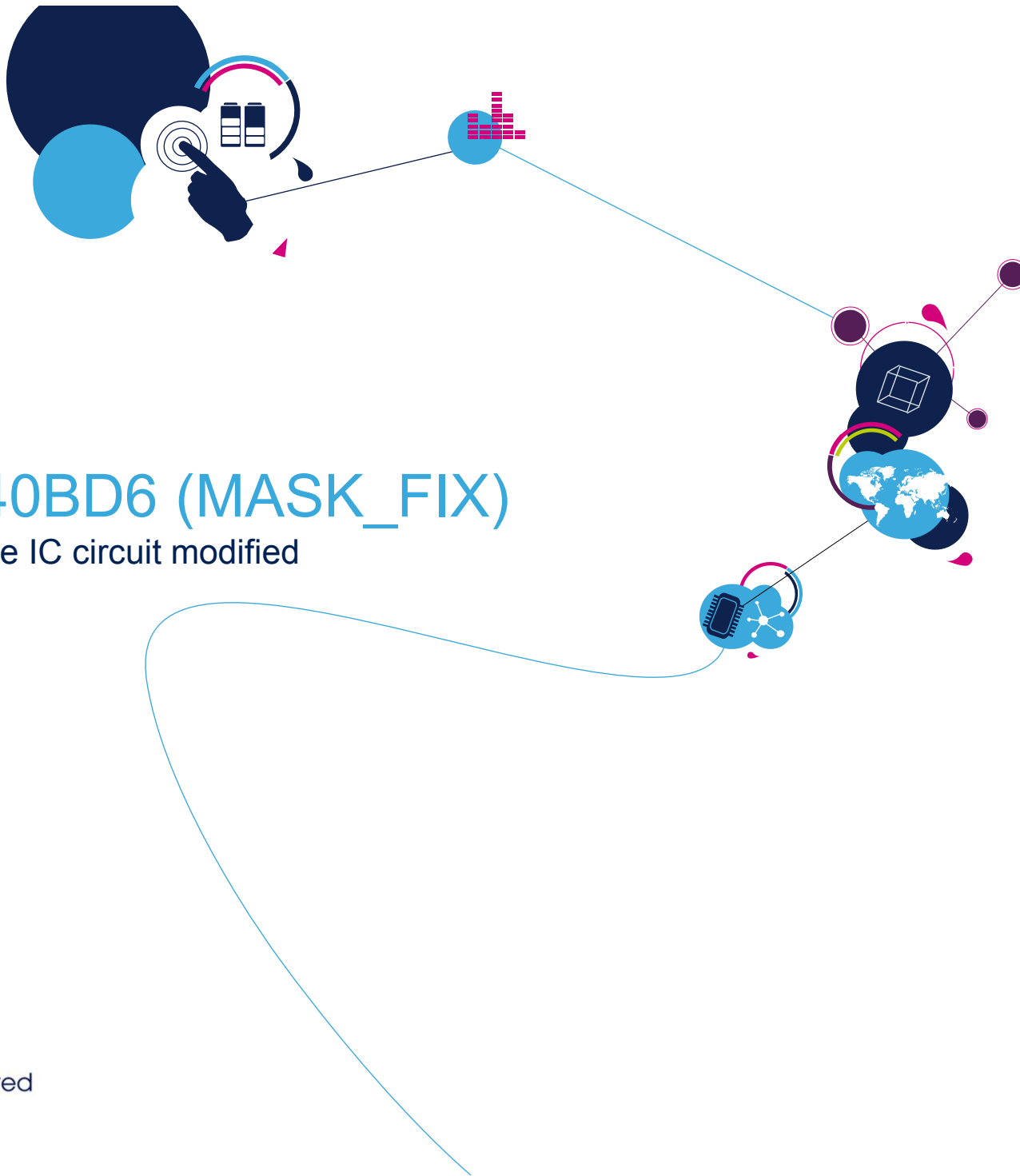
See the attached Report for the product reliability. Functional effectiveness has been confirmed by the application trial results.

### **IMPACTS of the Change**

Form: No impact

Fit: No impact

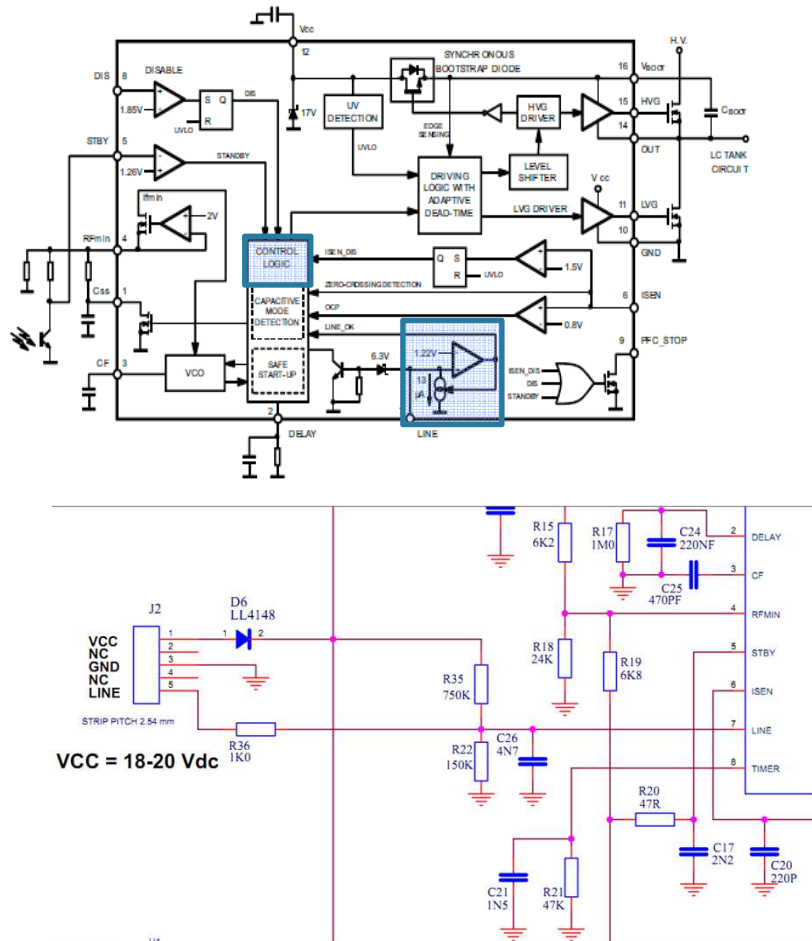
Function: yes, improved.



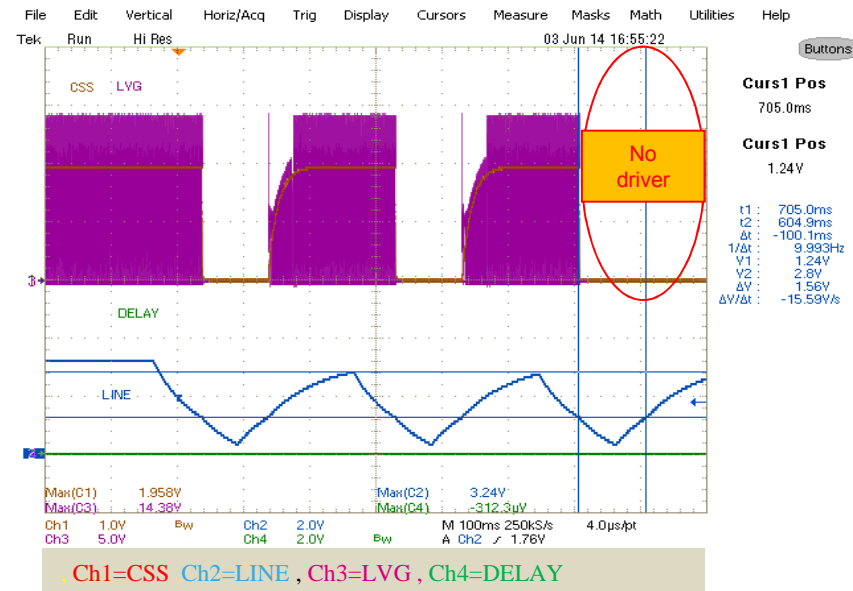
# L6699D U340BD6 (MASK\_FIX)

Summary Report of the IC circuit modified

# Partial schematic from application



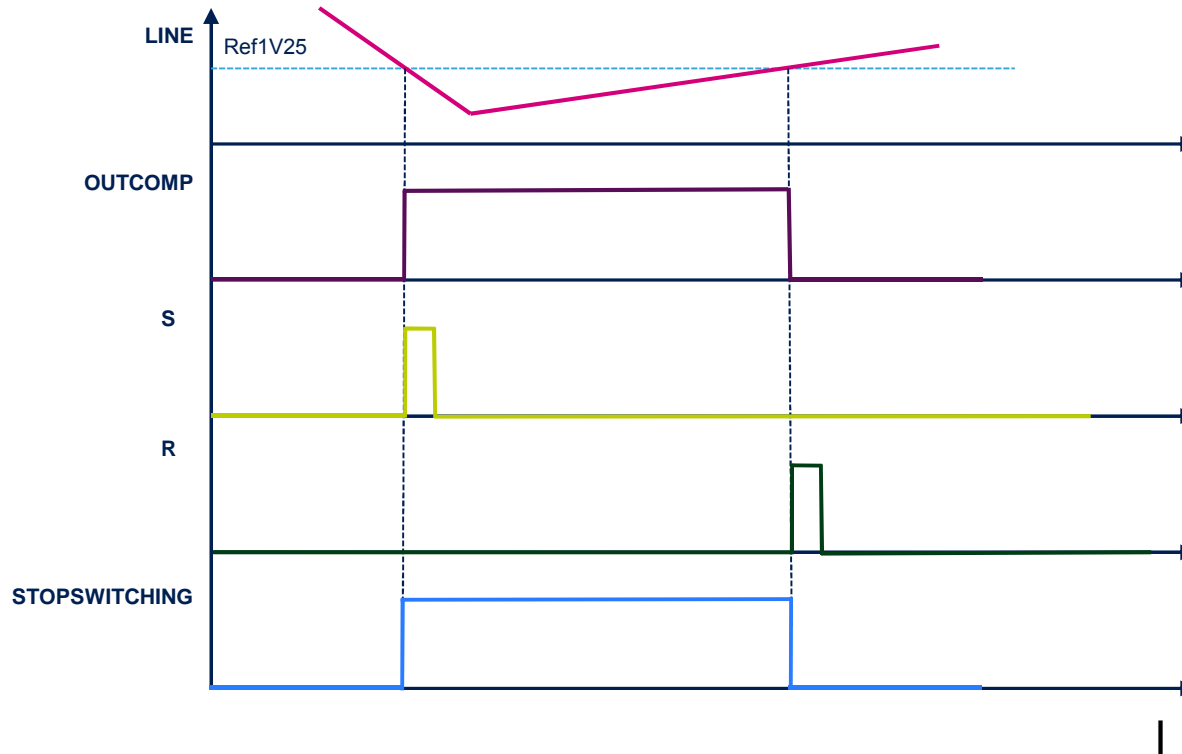
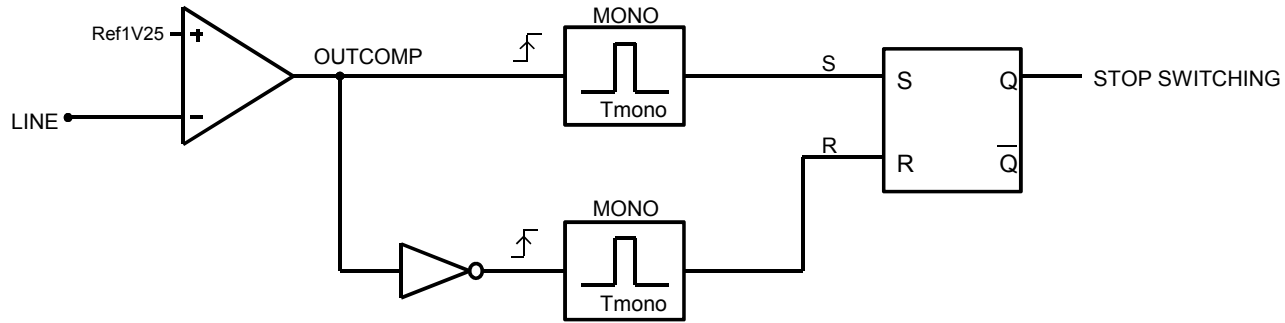
- When LINE pin of L6699 is used as IC disable with a  $dv/dt < 100V/s$ , sometimes we can find that power did not turn on for Vline higher than 1.25V.



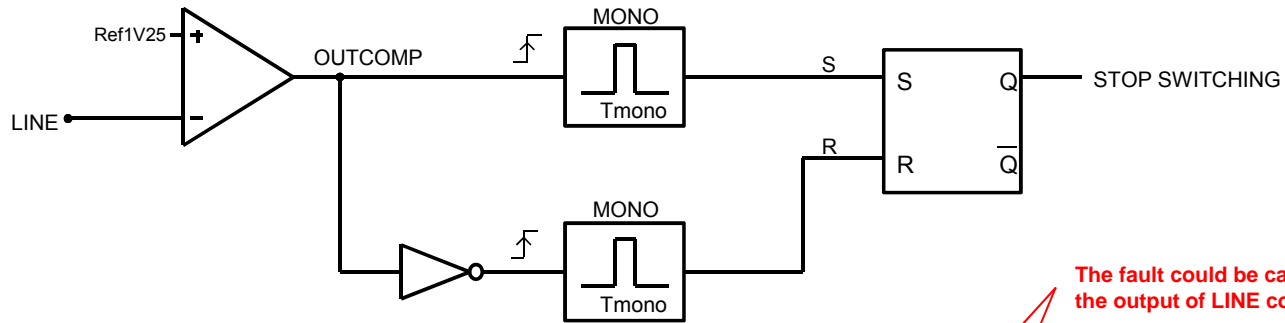
ST confidential



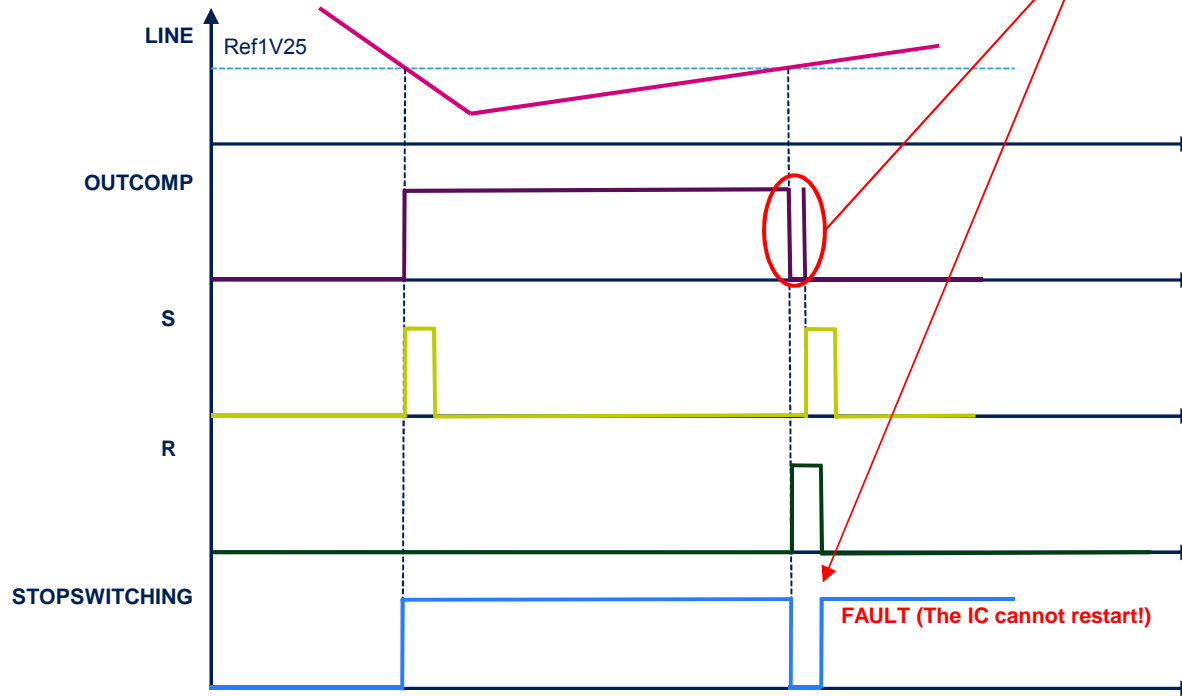
# Correct stop and restart switching by LINE



# Fault on restart switching by LINE

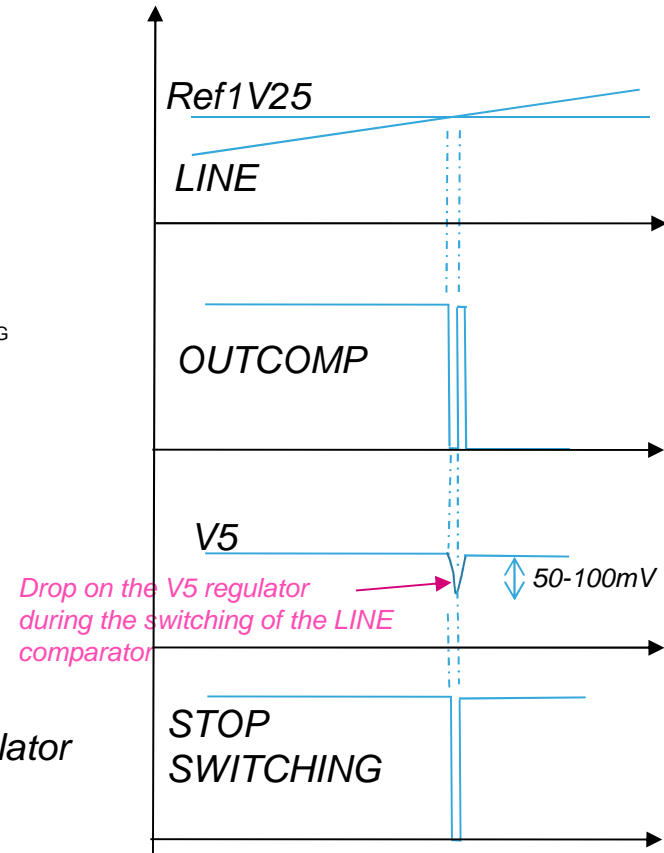
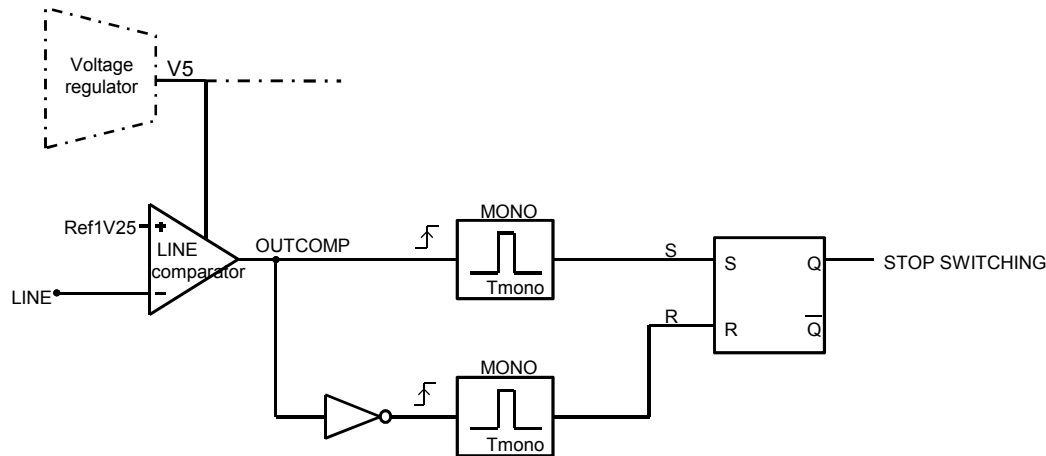


The fault could be caused by a glitch on the output of LINE comparator.



# Root-cause of the glitch

5

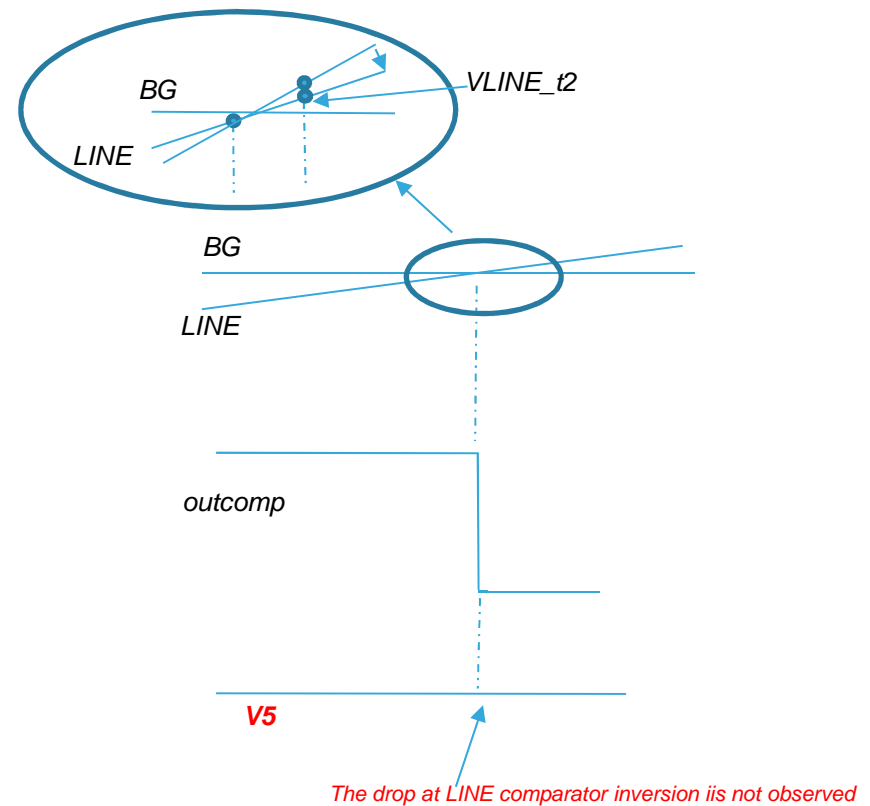
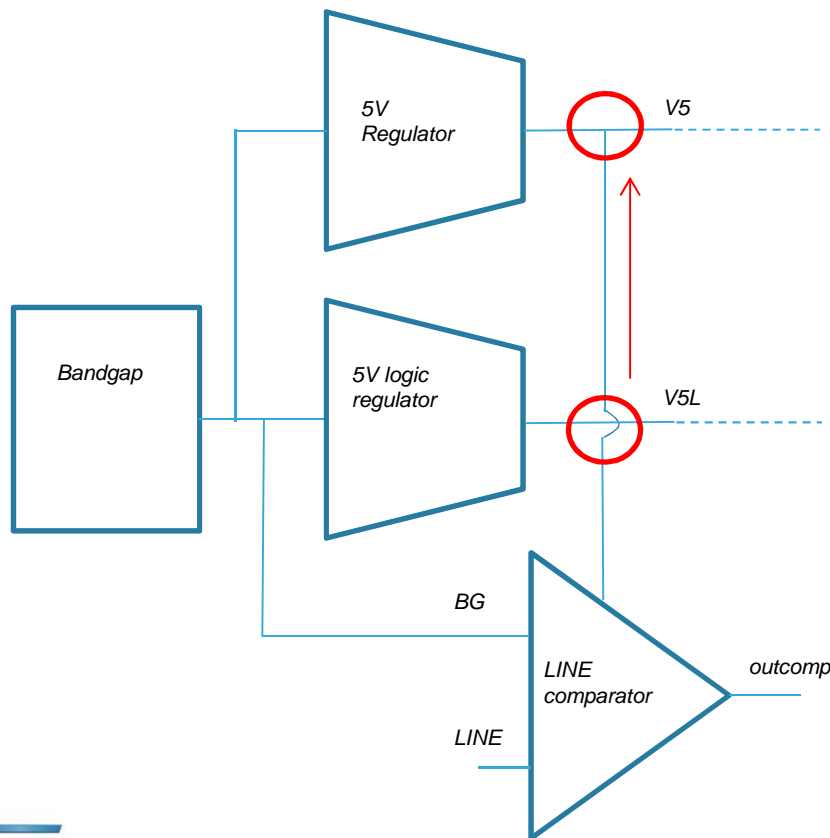


*The glitch on the output of the LINE comparator occurs with low slopes of the LINE signal and it is due to the drop of the V5 regulator during the commutation.*

*The occurrence of the glitch depends on the slope of the LINE signal. (Below a slope limit the glitch appears always due to V5 drop and because the LINE voltage is closer to the Ref1V25 during the commutation of the comparator.)*

# Implemented Fix

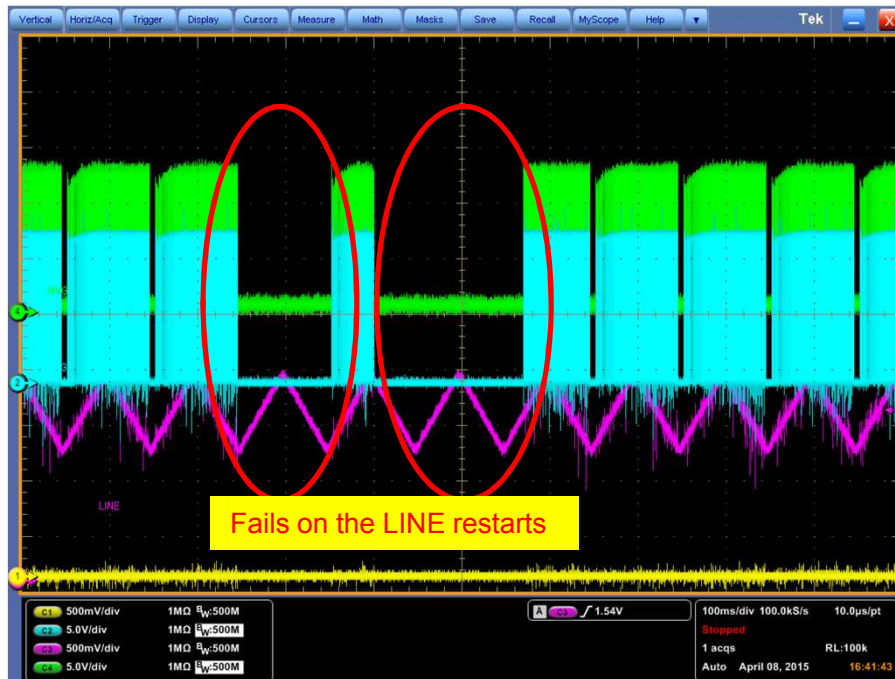
- To avoid the problem the Line Comparator supply has been replaced by an internal 5V regulator with a stronger current capability.



# IC Design Validation: U340BD6 vs U340BC6

## Plastic sample – Demo Board

### U340BC6 Old Silicon version



CH1: Idrain HVG

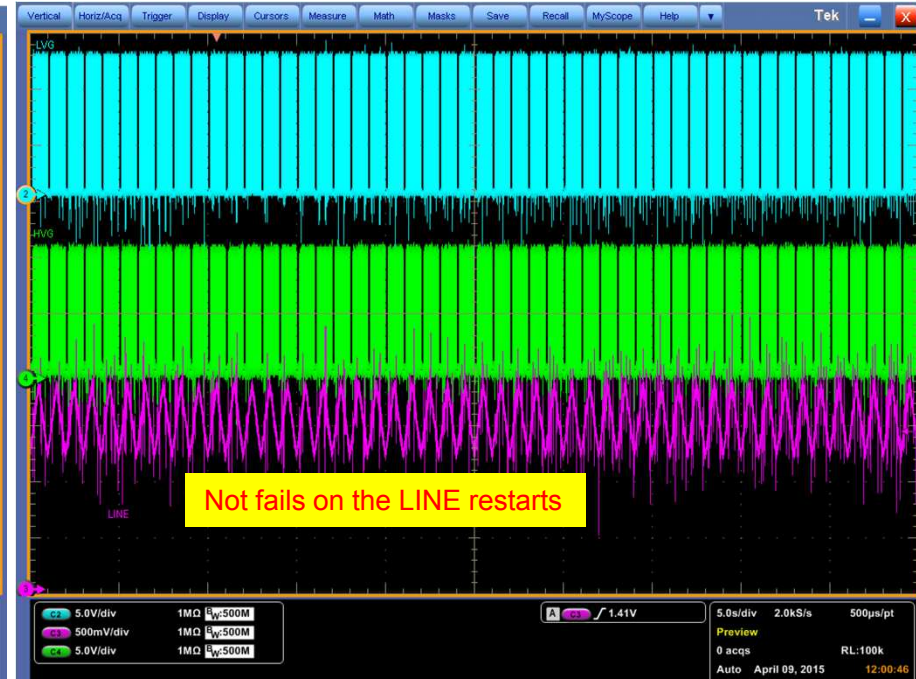
CH2:LVG

CH3

CH4:HVG

- U340BC6. With  $dV_{LINE}/dt < 100V/s$ , sometimes we can find that power did not turn on during the cross of LINE threshold of 1.25V.

### U340BD6 New Silicon version



CH1: Idrain HVG

CH2:LVG

CH3

CH4:HVG

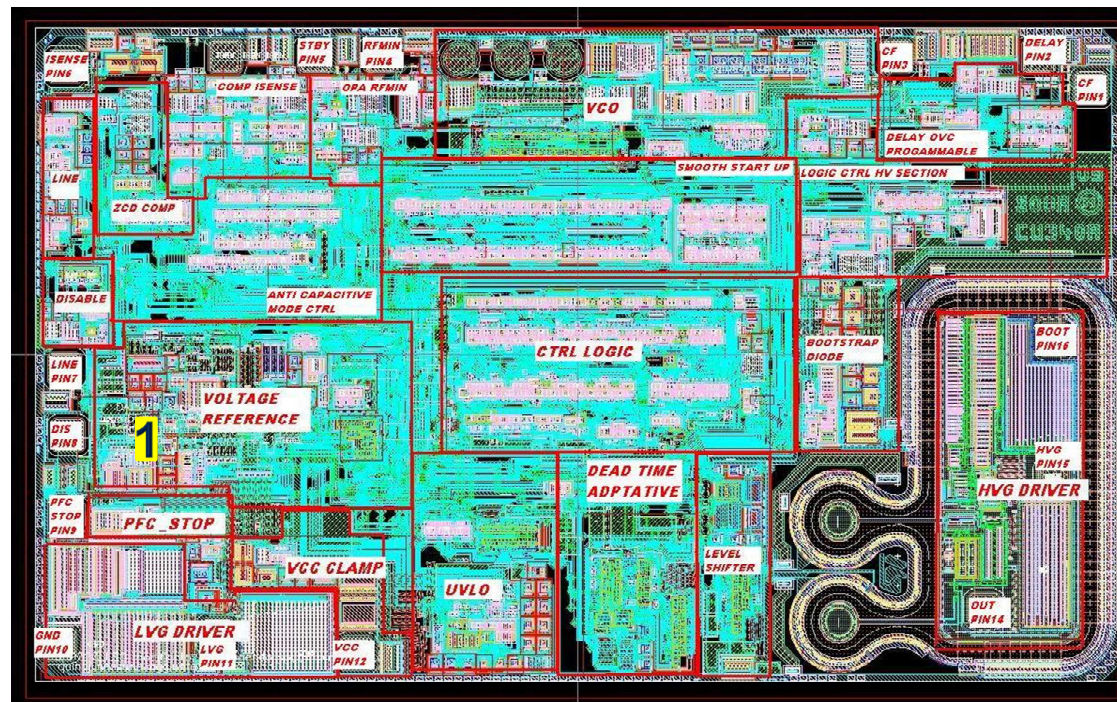
- U340BD6. With  $dV_{LINE}/dt < 100V/s$ , the IC always restarts when the threshold of LINE (1.25V) is crossed.

ST Internal

# From U340BC6 to U340BD6

- 1.U340BD BCDOFFLINE Masks fixed
- 2.Mask changed: poly2,contact,metal1
- 3.No spec changed/No critical metal path VCC, GND or ESD protection

FUNTIONS / BUGS	U340BC6	U340BD6
1) The IC does not re-enable when the voltage LINE threshold is crossed with dV/dt very slow.	Noise of the output logic LINE, supplied by V5L (internal voltage regulator).	Logic LINE comparator is supplied by a different internal voltage regulator with a current capability higher than V5L to increase the noise immunity.





# Reliability Report

General Information	
<b>Product Line</b>	<i>U340</i>
<b>Product Description</b>	<i>Enhanced high-voltage resonant controller</i>
<b>Product division</b>	<i>I&amp;PC</i>
<b>Package</b>	<i>SO16N</i>
<b>Silicon process technology</b>	<i>BCD OFF LINE</i>

Locations	
<b>Wafer fab location</b>	<i>ANG MO KIO</i>
<b>Assembly plant location</b>	<i>AMKOR ATP1 PHILIPPINES</i>
<b>Reliability assessment</b>	<i>Pass</i>

## DOCUMENT HISTORY

Version	Date	Pages	Author	Comment
1.0	17-April-2015	12	G. Capodici	Original document

Reviewed by

***Alceo Paratore***

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## 1 APPLICABLE AND REFERENCE DOCUMENTS

Document reference	Short description
AEC-Q100	: Stress test qualification for integrated circuits
8161393A	: General Specification For Product Development

## 2 RELIABILITY EVALUATION OVERVIEW

### 2.1 Objectives

This report contains the reliability activity done on the U340 device diffused in ANG MO KIO and assembled in SO16N in AMKOR ATP1 PHILIPPINES.

According to Reliability Qualification Plan, below is the list of the trials performed:

#### Die Oriented Tests

- High Temperature Operating Life test
- High Temperature Reverse Bias
- Temperature Humidity Bias

#### Package Oriented Tests

- Preconditioning

#### Electrical Characterization

- ESD resistance test
- LATCH-UP resistance test

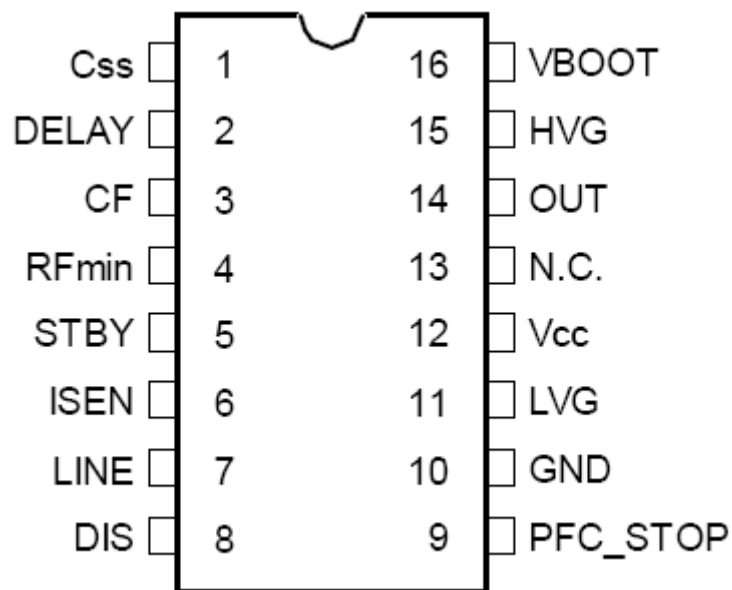
### 2.2 Conclusion

Taking in account the results of the trials performed **the U340 diffused in ANG MO KIO and assembled in SO16N in AMKOR ATP1 PHILIPPINES can be qualified from reliability viewpoint.**

### 3 DEVICE CHARACTERISTICS

#### 3.1 Device description

##### 3.1.1 Pin connection

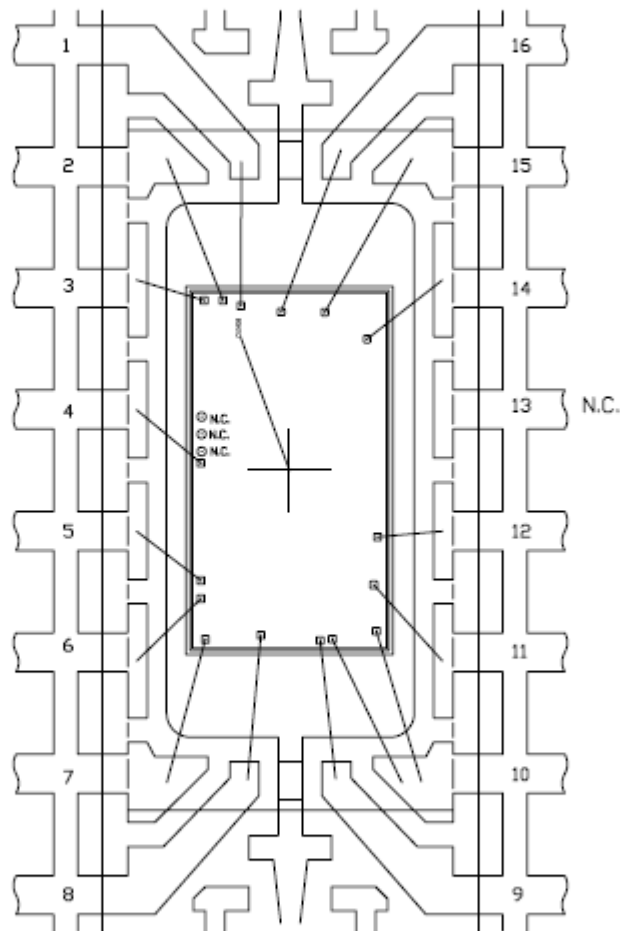


### 3.1.2 Bonding diagram

## MOUNT & BONDING DIAGRAM for line:U340

FRAME PAD: 102 X 220 mils  
2.591 X 5.588 mm

PK: Q7



SCALE  
1mm

BOND DIAGRAM, 16 LEAD, MATRIX SOIC, .150" BODY,  
.102" X .220" PAD, ETCHED, PLATING OPTIONS

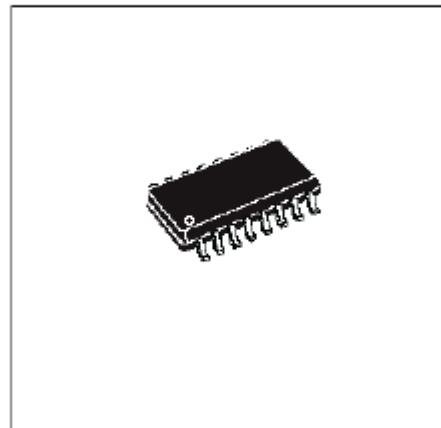
E.S.D PROGRAM is MANDATORY

### 3.1.3 Package outline/Mechanical data

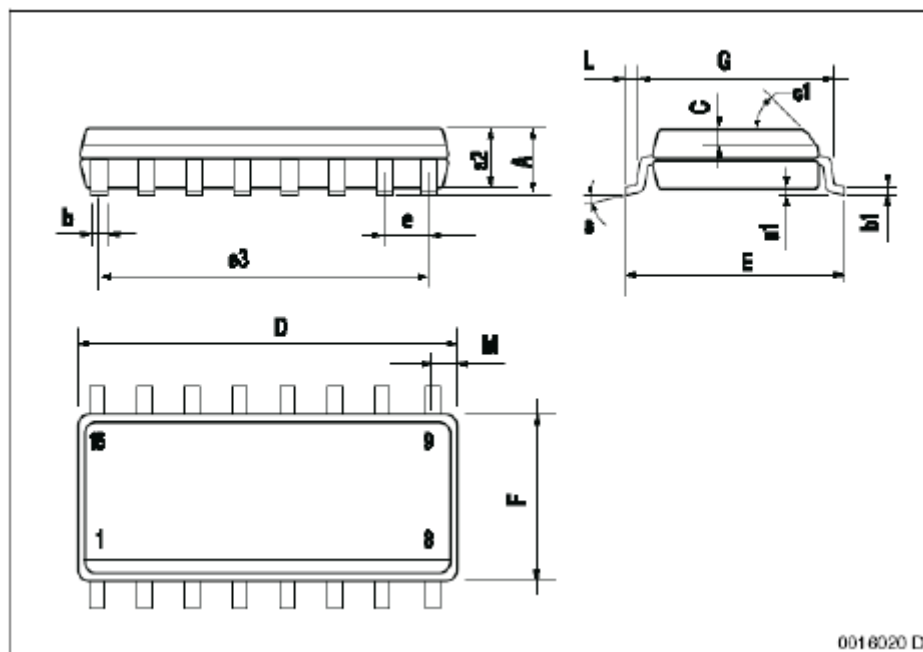
DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			1.75			0.069
a1	0.1		0.25	0.004		0.009
a2			1.6			0.063
b	0.35		0.46	0.014		0.018
b1	0.19		0.25	0.007		0.010
C		0.5			0.020	
c1			45°	(typ.)		
D(1)	9.8		10	0.386		0.394
E	5.8		6.2	0.228		0.244
e		1.27			0.050	
e3		8.89			0.350	
F(1)	3.8		4.0	0.150		0.157
G	4.60		5.30	0.181		0.208
L	0.4		1.27	0.150		0.050
M			0.82			0.024
S	8° (max.)					

(1) 'D' and 'F' do not include mold flash or protrusions - Mold flash or protrusions shall not exceed 0.15mm (.006inc.)

OUTLINE AND MECHANICAL DATA



SO16 (Narrow)



## 4 TRACEABILITY

Wafer fab information	
Wafer fab manufacturing location	ANG MO KIO
Wafer diameter	6 inches
Wafer thickness	375 $\mu$ m
Silicon process technology	BCD OFF LINE
Die finishing back side	Cr/Ni
Die size	3870x2190 $\mu$ m
Bond pad metallization layers	AlSiCu
Passivation	SiN
Metal levels	1

Assembly Information	
Assembly plant location	AMKOR ATP1 PHILIPPINES
Package description	SO16N
Molding compound	SUMITOMO G600
Wires bonding materials/diameters	Au / 1mils
Die attach material	ABLESTICK 8290
Lead solder material	Sn

## 5 TESTS RESULTS SUMMARY

### 5.1 Test plan and results summary

Test	Test short description					Results Fail/SS
	Method	Conditions	Sample/Lots	Number of lots	Duration	
PC	Pre-Conditioning: Moisture sensitivity level 3					0/157
		192h 30°C/60%RH- 3 reflow PBT 260°C	157	1	-	
HTRB	High Temperature Reverse Bias - Positive					0/40
		Conditions : Vs=600V, VCC=16V Tj=150 °C;	40	1	1000h	
HTOL	High Temperature Operating Life Test					0/77
	PC before	Vs=580V, VCC=16V, Tj=150 °C;	77	1	1000h	
THB	Temperature Humidity Bias					0/40
	PC before	Vs=100V, VCC=16V, Ta=85°C / 85%R.H.;	40	1	1000h	
ESD	Electro Static Discharge					0/3
	Human Body Model	+/- 2KV	3	1	-	
	Machine Model	+/- 100V	3	1	-	
	Charge Device Model	+/- 750V	3	1	-	
LU	Latch-Up					0/3
		Over-voltage and Current Injection (Jedec78) performed at 85°C Class 2B	3	1	-	

All above trials performed on BA6 revision.

## **5.2 Die oriented tests**

### **5.2.1 High Temperature Operating Life Test**

This test is performed like application conditions in order to check electromigration phenomena, gate oxide weakness and other design/manufacturing defects put in evidence by internal power dissipation.

The flow chart is the following:

- Initial testing @ Ta=25°C
- Check @ 168 and 500hrs @ Ta=25°C
- Final Testing @ 1000hrs @ Ta=25°C

### **5.2.2 High Temperature Reverse Bias**

This test is performed to evaluate die problems related with chip stability, layout structure, surface contamination and oxide faults.

The flow chart is the following:

- Initial testing @ Ta=25°C
- Check @ 168 and 500hrs @ Ta=25°C
- Final Testing @ 1000hrs @ Ta=25°C

### **5.2.3 Temperature Humidity Bias**

The test is addressed to put in evidence problems of the die-package compatibility related to phenomena activated in wet conditions such as electro-chemical corrosion.

The device is stressed in static configuration approaching some field status like power down. Temperature, Humidity and Bias are applied to the device in the following environmental conditions => Ta=85°C / RH=85%.

Input pins to Low / High Voltage (alternate) to maximize voltage contrast.

Test Duration 1000 h.

The flow chart is the following:

- Initial testing @ Ta=25°C
- Check @ 168 and 500hrs @ Ta=25°C
- Final Testing @ 1000hrs @ Ta=25°C



## **5.3 Package oriented tests**

### **5.3.1 Pre-Conditioning**

The device is submitted to a typical temperature profile used for surface mounting, after a controlled moisture absorption.

The scope is to verify that the surface mounting stress does not impact on the subsequent reliability performance. The typical failure modes are "pop corn" effect and delamination.

## 5.4 Electrical Characterization Tests

### 5.4.1 Latch-up

This test is intended to verify latch-up sensitivity for new product or new process qualification.

Method applied:  $I_p = \pm 100\text{mA}$  for each pin according to 0018695 S.T. spec. (referring to Jedec Std-78).

The flow chart is the following:

- Initial testing @  $T_a=25^\circ\text{C}$
- Latch-up trail performed @  $T_a=25^\circ\text{C}$
- Final Testing @  $T_a=25^\circ\text{C}$

Condition	NEG. INJECTION	POS. INJECTION	OVERVOLTAGE
<i>IN low: 0V</i>	-30mA	$I_{nom}+100\text{mA}$	VCC= 17V BOOT= 17V
<i>IN high: 0.7V</i>	-30mA	$I_{nom}+100\text{mA}$	VCC= 17V BOOT= 17V

### 5.4.2 E.S.D.

This test is performed to verify adequate pin protection to electrostatic discharges.

The flow chart is the following:

- Initial testing @  $T_a=25^\circ\text{C}$
- ESD discharging @  $T_a=25^\circ\text{C}$
- Final Testing @  $T_a=25^\circ\text{C}$

TEST CONDITIONS:

- **Human Body Model** JEDEC STANDARD JESD22-A114  
CDF-AEC-Q100-002
- **Machine Model** JEDEC STANDARD EIA/JESD-A115  
CDF-AEC-Q100-003
- **Charge Device Model** ANSI/ESD STM 5.3.1 ESDA  
CDF-AEC-Q100-011